# MOSFET – Power, Single N-Channel 40 V, 3.3 m $\Omega$ , 102 A

#### **Features**

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- NVMFS5C450NWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

| ,   |                                     |                        |                                   |                 |      |
|---|-------------------------------------|------------------------|-----------------------------------|-----------------|------|
| Parameter   |                                     |                        | Symbol                            | Value           | Unit |
| Drain-to-Source Voltage   |                                     |                        | $V_{DSS}$                         | 40              | ٧    |
| Gate-to-Source Voltage  | Э                                   |                        | $V_{GS}$                          | ±20             | V    |
| Continuous Drain  |                                     | T <sub>C</sub> = 25°C  | I <sub>D</sub>                    | 102             | Α    |
| Current R <sub>θJC</sub> (Notes 1, 3)   | Steady                              | T <sub>C</sub> = 100°C |                                   | 72              |      |
| Power Dissipation   | State                               | T <sub>C</sub> = 25°C  | $P_{D}$                           | 68              | W    |
| R <sub>θJC</sub> (Note 1)   |                                     | T <sub>C</sub> = 100°C |                                   | 34              |      |
| Continuous Drain  |                                     | T <sub>A</sub> = 25°C  | I <sub>D</sub>                    | 24              | Α    |
| Current R <sub>θJA</sub> (Notes 1, 2, 3)                                      | Steady                              | T <sub>A</sub> = 100°C |                                   | 17              |      |
| Power Dissipation   | State                               | T <sub>A</sub> = 25°C  | $P_{D}$                           | 3.6             | W    |
| R <sub>θJA</sub> (Notes 1 & 2)  |                                     | T <sub>A</sub> = 100°C |                                   | 1.8             |      |
| Pulsed Drain Current  | $T_A = 25^{\circ}C, t_p = 10 \mu s$ |                        | I <sub>DM</sub>                   | 554             | Α    |
| Operating Junction and Storage Temperature                                    |                                     |                        | T <sub>J</sub> , T <sub>stg</sub> | -55 to<br>+ 175 | °C   |
| Source Current (Body Diode)   |                                     |                        | I <sub>S</sub>                    | 65              | Α    |
| Single Pulse Drain-to-Source Avalanche<br>Energy (I <sub>L(pk)</sub> = 7.0 A) |                                     |                        | E <sub>AS</sub>                   | 215             | mJ   |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s)             |                                     | TL                     | 260                               | °C              |      |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter                                   | Symbol          | Value | Unit |
|---|-----------------|-------|------|
| Junction-to-Case - Steady State             | $R_{\theta JC}$ | 2.2   | °C/W |
| Junction-to-Ambient - Steady State (Note 2) | $R_{\theta JA}$ | 41    |      |

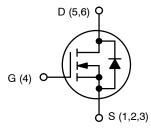
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



#### ON Semiconductor®

#### www.onsemi.com

| V <sub>(BR)DSS</sub> | R <sub>DS(ON)</sub> MAX | I <sub>D</sub> MAX |
|----------------------|-------------------------|--------------------|
| 40 V                 | 3.3 m $\Omega$ @ 10 V   | 102 A              |



**N-CHANNEL MOSFET** 



DIAGRAM

D
S
S
XXXXXX
S
AYWZZ
G
D

**MARKING** 

XXXXXX = 5C450N

(NVMFS5C450N) or

450NWF

(NVMFS5C450NWF)

A = Assembly Location Y = Year

W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

| Parameter  | Symbol                                   | Test Condition   |                        | Min | Тур      | Max | Unit    |
|--|--|--|------------------------|-----|----------|-----|---------|
| OFF CHARACTERISTICS  | •  |  |                        | -   | <u>-</u> | -   | -       |
| Drain-to-Source Breakdown Voltage                            | V <sub>(BR)DSS</sub>                     | $V_{GS}$ = 0 V, $I_D$ = 250 $\mu A$  |                        | 40  |          |     | V       |
| Drain-to-Source Breakdown Voltage<br>Temperature Coefficient | V <sub>(BR)DSS</sub> /<br>T <sub>J</sub> |  |                        |     | 20       |     | mV/°C   |
| Zero Gate Voltage Drain Current                              | I <sub>DSS</sub>                         | V <sub>GS</sub> = 0 V,   |                        |     |          | 10  |         |
|  |  | V <sub>DS</sub> = 40 V   | T <sub>J</sub> = 125°C |     |          | 100 | μΑ      |
| Gate-to-Source Leakage Current                               | I <sub>GSS</sub>                         | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V                                      |                        |     |          | 100 | nA      |
| ON CHARACTERISTICS (Note 4)                                  |  |  |                        |     |          |     |         |
| Gate Threshold Voltage                                       | V <sub>GS(TH)</sub>                      | $V_{GS} = V_{DS}, I_D$   | = 65 μΑ                | 2.5 |          | 3.5 | V       |
| Threshold Temperature Coefficient                            | V <sub>GS(TH)</sub> /T <sub>J</sub>      |  |                        |     | -9.1     |     | mV/°C   |
| Drain-to-Source On Resistance                                | R <sub>DS(on)</sub>                      | V <sub>GS</sub> = 10 V   | I <sub>D</sub> = 50 A  |     | 2.7      | 3.3 | mΩ      |
| Forward Transconductance                                     | 9FS                                      | V <sub>DS</sub> =15 V, I <sub>D</sub> = 50 A                                       |                        |     | 93       |     | S       |
| CHARGES, CAPACITANCES & GATE RE                              | SISTANCE                                 |  |                        |     |          |     |         |
| Input Capacitance  | C <sub>ISS</sub>                         | $V_{GS} = 0 \text{ V, f} = 1 \text{ MHz, } V_{DS} = 25 \text{ V}$                  |                        |     | 1600     |     |         |
| Output Capacitance   | C <sub>OSS</sub>                         |  |                        |     | 830      |     | pF      |
| Reverse Transfer Capacitance                                 | C <sub>RSS</sub>                         |  |                        |     | 28       |     |         |
| Total Gate Charge  | Q <sub>G(TOT)</sub>                      | V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 50 A              |                        |     | 23       |     |         |
| Threshold Gate Charge  | Q <sub>G(TH)</sub>                       | V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 50 A              |                        |     | 5.1      |     | nC      |
| Gate-to-Source Charge  | Q <sub>GS</sub>                          |  |                        |     | 9.0      |     |         |
| Gate-to-Drain Charge   | $Q_{GD}$                                 |  |                        |     | 3.5      |     |         |
| Plateau Voltage  | V <sub>GP</sub>                          |  |                        |     | 5.3      |     | V       |
| SWITCHING CHARACTERISTICS (Note 5                            | )  |  |                        |     |          |     |         |
| Turn-On Delay Time   | t <sub>d(ON)</sub>                       |  |                        |     | 10       |     |         |
| Rise Time  | t <sub>r</sub>                           | $V_{GS}$ = 10 V, $V_{DS}$ = 20 V,<br>$I_D$ = 50 A, $R_G$ = 2.5 $\Omega$            |                        |     | 47       |     |         |
| Turn-Off Delay Time  | t <sub>d(OFF)</sub>                      |  |                        |     | 19       |     | ns<br>- |
| Fall Time  | t <sub>f</sub>                           |  |                        |     | 3.0      |     |         |
| DRAIN-SOURCE DIODE CHARACTERIS                               | TICS                                     |  |                        |     |          |     |         |
| Forward Diode Voltage  | V <sub>SD</sub>                          | V <sub>GS</sub> = 0 V,   | T <sub>J</sub> = 25°C  |     | 0.9      | 1.2 | .,,     |
|  |  | I <sub>S</sub> = 50 A  | T <sub>J</sub> = 125°C |     | 0.78     |     | \ \     |
| Reverse Recovery Time  | t <sub>RR</sub>                          | $V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$ |                        |     | 37       |     |         |
| Charge Time  | ta                                       |  |                        |     | 18       |     | ns      |
| Discharge Time   | t <sub>b</sub>                           |  |                        |     | 19       |     |         |
| Reverse Recovery Charge                                      | Q <sub>RR</sub>                          |  |                        |     | 23       |     | nC      |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%.

<sup>5.</sup> Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**

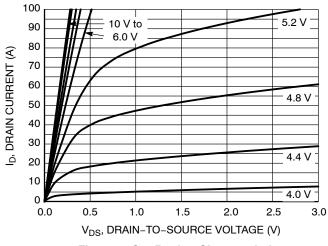


Figure 1. On-Region Characteristics

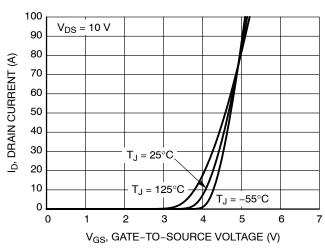


Figure 2. Transfer Characteristics

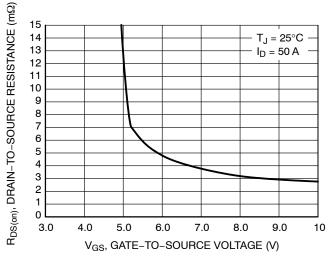


Figure 3. On-Resistance vs. Gate-to-Source Voltage

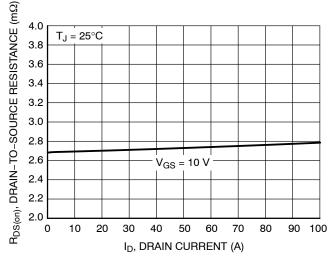


Figure 4. On-Resistance vs. Drain Current and **Gate Voltage** 

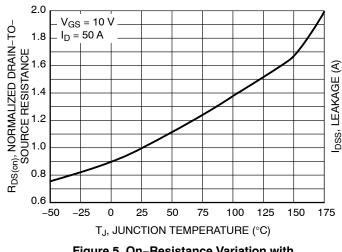


Figure 5. On-Resistance Variation with **Temperature** 

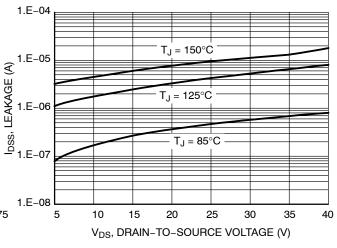


Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### **TYPICAL CHARACTERISTICS**

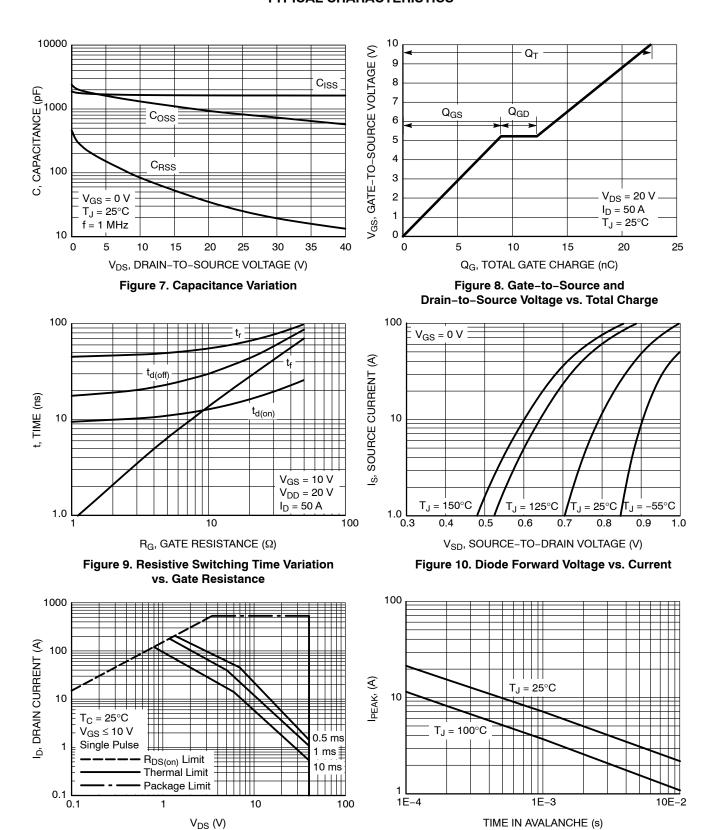


Figure 12. I<sub>PEAK</sub> vs. Time in Avalanche

Figure 11. Safe Operating Area

## **TYPICAL CHARACTERISTICS**

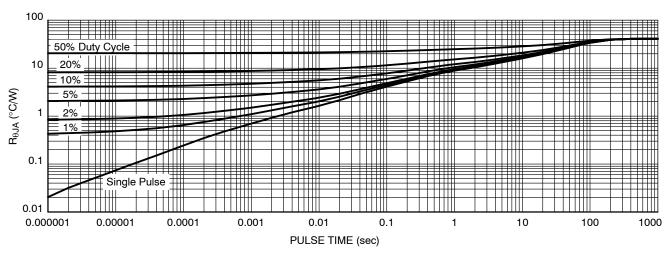


Figure 13. Thermal Characteristics

#### **DEVICE ORDERING INFORMATION**

| Device             | Marking | Package                            | Shipping <sup>†</sup> |
|--------------------|---------|------------------------------------|-----------------------|
| NVMFS5C450NT1G     | 5C450N  | DFN5<br>(Pb-Free)                  | 1500 / Tape & Reel    |
| NVMFS5C450NWFT1G   | 450NWF  | DFN5<br>(Pb-Free, Wettable Flanks) | 1500 / Tape & Reel    |
| NVMFS5C450NT3G     | 5C450N  | DFN5<br>(Pb-Free)                  | 5000 / Tape & Reel    |
| NVMFS5C450NWFT3G   | 450NWF  | DFN5<br>(Pb-Free, Wettable Flanks) | 5000 / Tape & Reel    |
| NVMFS5C450NAFT1G   | 5C450N  | DFN5<br>(Pb-Free)                  | 1500 / Tape & Reel    |
| NVMFS5C450NWFAFT1G | 450NWF  | DFN5<br>(Pb-Free, Wettable Flanks) | 1500 / Tape & Reel    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



0.10

0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

**DATE 25 JUN 2018** 

#### NOTES:

BURRS

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE

|     | MILLIMETERS |       |      |  |
|-----|-------------|-------|------|--|
| DIM | MIN         | NOM   | MAX  |  |
| Α   | 0.90        | 1.00  | 1.10 |  |
| A1  | 0.00        |       | 0.05 |  |
| b   | 0.33        | 0.41  | 0.51 |  |
| С   | 0.23        | 0.28  | 0.33 |  |
| D   | 5.00        | 5.15  | 5.30 |  |
| D1  | 4.70        | 4.90  | 5.10 |  |
| D2  | 3.80        | 4.00  | 4.20 |  |
| E   | 6.00        | 6.15  | 6.30 |  |
| E1  | 5.70        | 5.90  | 6.10 |  |
| E2  | 3.45        | 3.65  | 3.85 |  |
| е   | 1.27 BSC    |       |      |  |
| G   | 0.51        | 0.575 | 0.71 |  |
| K   | 1.20        | 1.35  | 1.50 |  |
| L   | 0.51        | 0.575 | 0.71 |  |
| L1  | 0.125 REF   |       |      |  |
| M   | 3.00        | 3.40  | 3.80 |  |
| A   | 0 0         |       | 12 ° |  |

#### **GENERIC** MARKING DIAGRAM\*



XXXXXX = Specific Device Code

= Assembly Location Α

Υ = Year W = Work Week ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





**DETAIL A** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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|------------------|--------------------------|--|-------------|--|
| DESCRIPTION:     | DFN5 5x6, 1.27P (SO-8FL) |  | PAGE 1 OF 1 |  |

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# onsemi:

NVMFS5C450NAFT3G NVMFS5C450NAFT1G NVMFS5C450NWFAFT3G NVMFS5C450NWFAFT3G NVMFS5C450NWF3G NVMFS5C450NWFT3G NVMFS5C450NWFT3G